



Doc.# : PC#202010

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Asahi Kasei Microdevices Corporation

Notice of Additional Material Source for Assembly

Asahi Kasei Microdevices Corporation announces the addition of the material source at our contract assembly site.

We would appreciate your understanding and corporations referring to the below detail and schedule.

Sincerely

Items	Please see the below list.		
Change Item	Additional source of the mold resin		
Reason	For business continuity		
Schedule	Sample available	:	December, 2020
	Reliability Test Completion	:	January, 2021
	Customer Approval	:	March, 2021
	Start of Shipment	:	June, 2021 or later

	Current	Additional Source
Supplier	Company A	Company B
Halogen	Free	No change
Component	Epoxy Resin: OCN Filler material: Fused Silica, Grinded/Spherical mixture Flame Retardant: Metallic Hydroxide	No change
Tg	165°C	155°C
Flexural Strength (Room Temperature)	120Mpa	140Mpa
Flexural Modulus (Room Temperature)	19,000Mpa	16,500MPa



No.	Current P/N
1	HW101A
2	HW102A
3	HW108A
4	HW300B

End

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